



**THE DATASHEET OF
RS1KFSHMWG**



1A, 200V - 1000V Surface Mount Fast Recovery Rectifier

FEATURES

- Glass passivated junction chip
- Ideal for automated placement
- Low profile package
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- High frequency rectification
- Freewheeling application
- Switching mode converters and inverters in computer, automotive and telecommunication

MECHANICAL DATA

- Case: SOD-128
- Molding compound meets UL 94V-0 flammability rating
- Part no. with suffix "H" means AEC-Q101 qualified
- Packing code with suffix "G" means green compound (halogen-free)
- Moisture sensitivity level: level 1, per J-STD-020
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: As marked
- Weight: 0.027 g (approximately)

KEY PARAMETERS		
PARAMETER	VALUE	UNIT
$I_{F(AV)}$	1	A
V_{RRM}	200 - 1000	V
I_{FSM}	30	A
$T_{J\ MAX}$	150	°C
Package	SOD-128	
Configuration	Single die	



SOD-128

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)							
PARAMETER	SYMBOL	RS1DFS	RS1GFS	RS1JFS	RS1KFS	RS1MFS	UNIT
Marking code on the device		RS1DFS	RS1GFS	RS1JFS	RS1KFS	RS1MFS	
Repetitive peak reverse voltage	V_{RRM}	200	400	600	800	1000	V
Reverse voltage, total rms value	$V_{R(RMS)}$	140	280	420	560	700	V
Forward current	$I_{F(AV)}$	1					A
Surge peak forward current, 8.3 ms single half sine-wave superimposed on rated load per diode	I_{FSM}	30					A
Junction temperature	T_J	- 55 to +150					°C
Storage temperature	T_{STG}	- 55 to +150					°C

CHARACTERISTICS CURVES

($T_A = 25^\circ\text{C}$ unless otherwise noted)

Fig.1 Forward Current Derating Curve

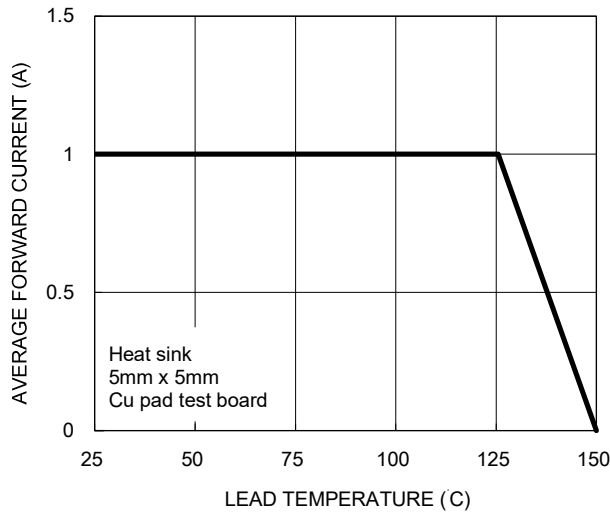


Fig.2 Typical Junction Capacitance

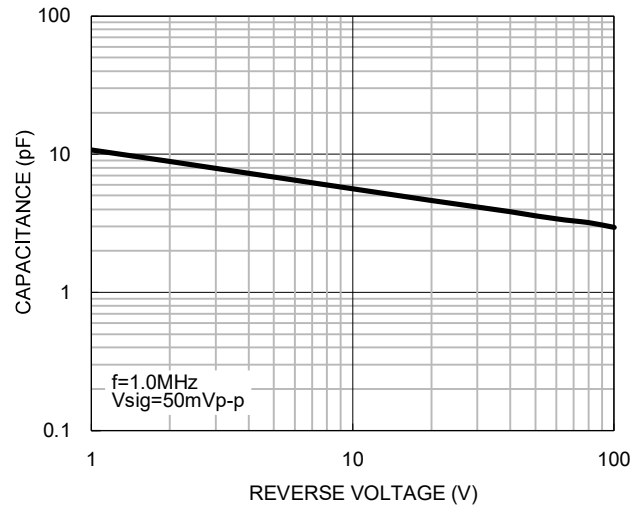


Fig.3 Typical Reverse Characteristics

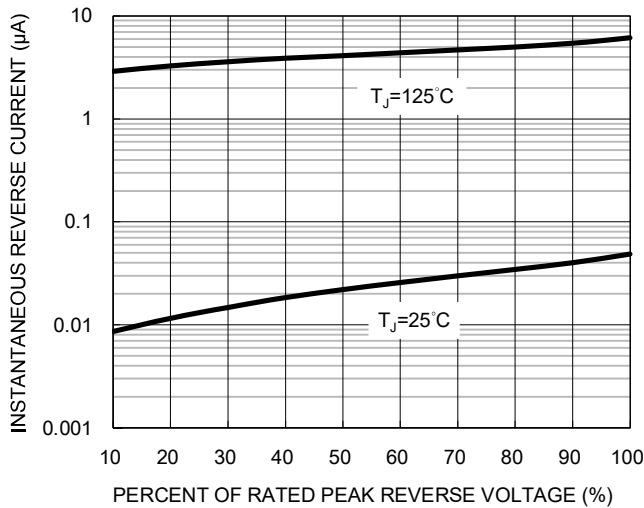
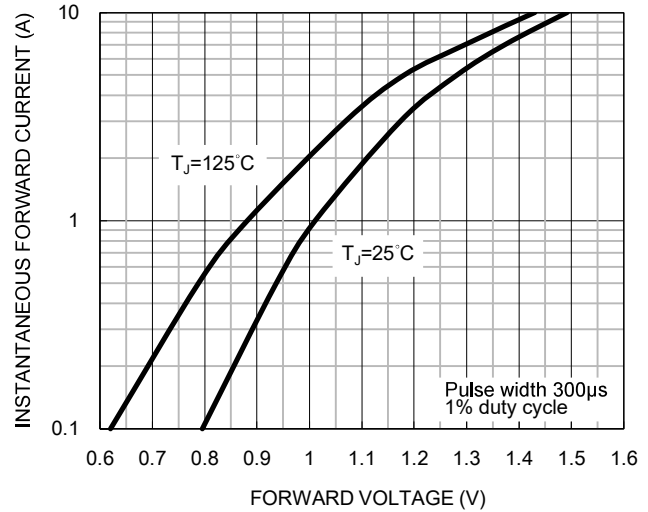
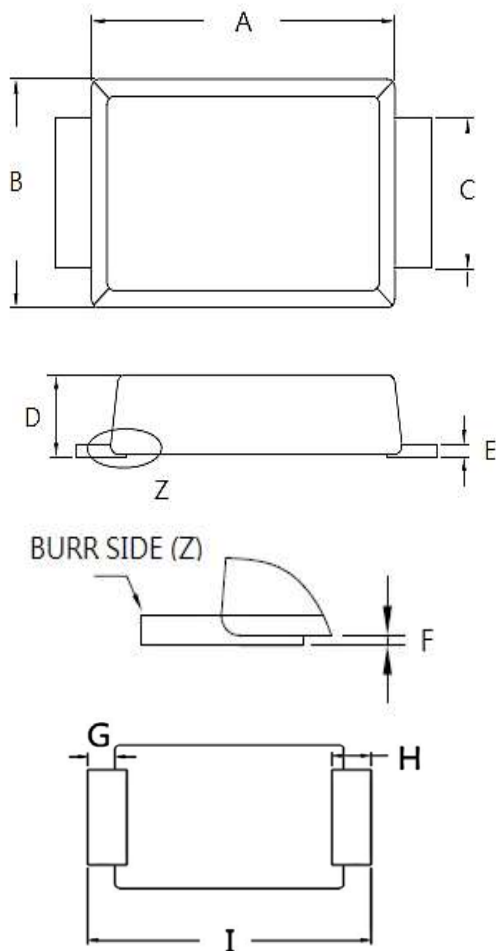


Fig.4 Typical Forward Characteristics



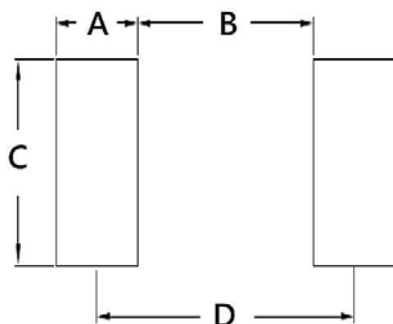
PACKAGE OUTLINE DIMENSIONS

SOD-128



DIM	Unit (mm)		Unit (inch)	
	Min	Max	Min	Max
A	3.60	4.00	0.142	0.157
B	2.30	2.70	0.091	0.106
C	1.60	1.90	0.063	0.075
D	0.90	1.10	0.035	0.043
E	0.10	0.22	0.004	0.009
F	0.00	0.10	0.000	0.004
G	0.30	0.60	0.012	0.024
H	0.40	0.80	0.016	0.031
I	4.40	5.00	0.173	0.197

SUGGESTED PAD LAYOUT



DIM	Unit (mm)	Unit (inch)
A	1.40	0.055
B	3.00	0.118
C	2.10	0.082
D	4.40	0.173

MARKING DIAGRAM



P/N = Marking Code
YW = Date Code
F = Factory Code

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